

TC74ACT374P, TC74ACT374F, TC74ACT374FW, TC74ACT374FT**OCTAL D - TYPE FLIP - FLOP WITH 3 - STATE OUTPUT**

The TC74ACT374 is an advanced high speed CMOS OCTAL FLIP-FLOP fabricated with silicon gate and double-layer metal wiring C²MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

This devices may be used as a level converter for interfacing TTL or NMOS to High Speed CMOS. The inputs are compatible with TTL, NMOS and CMOS output voltage levels. These 8-bit D-type flip-flops are controlled by a clock input (CK) and a output enable input ($\overline{OE}$).

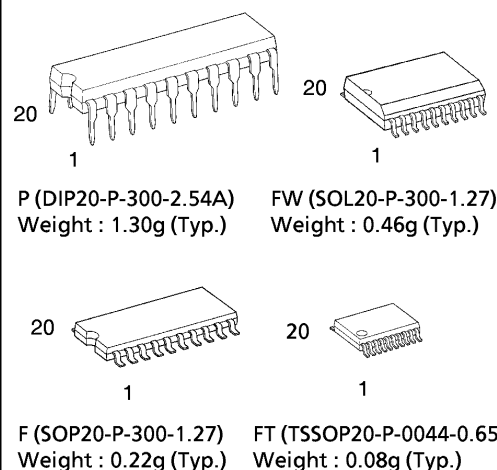
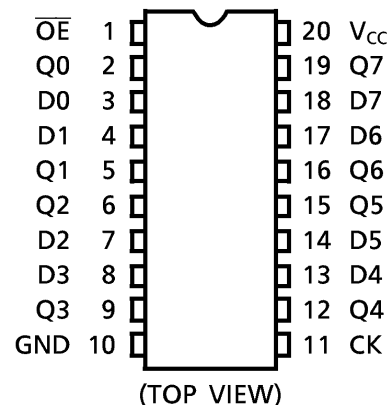
When the $\overline{OE}$ input is high, the eight outputs are in a high impedance state.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES:

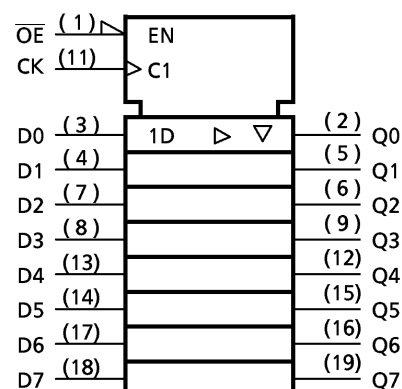
- High Speed..... $f_{MAX} = 180\text{MHz}$ (typ.)
at $V_{CC} = 5\text{V}$
- Low Power Dissipation..... $I_{CC} = 8\mu\text{A}$ (Max.) at $T_a = 25^\circ\text{C}$
- Compatible with TTL outputs.... $V_{IL} = 0.8\text{V}$ (Max.)
 $V_{IH} = 2.0\text{V}$ (Min.)
- Symmetrical Output Impedance... $|I_{OH}| = I_{OL} = 24\text{mA}$ (Min.)
Capability of driving 50Ω transmission lines.
- Balanced Propagation Delays..... $t_{PLH} \approx t_{PHL}$
- Pin and Function Compatible with 74F374

(Note) The JEDEC SOP (FW) is not available in Japan.

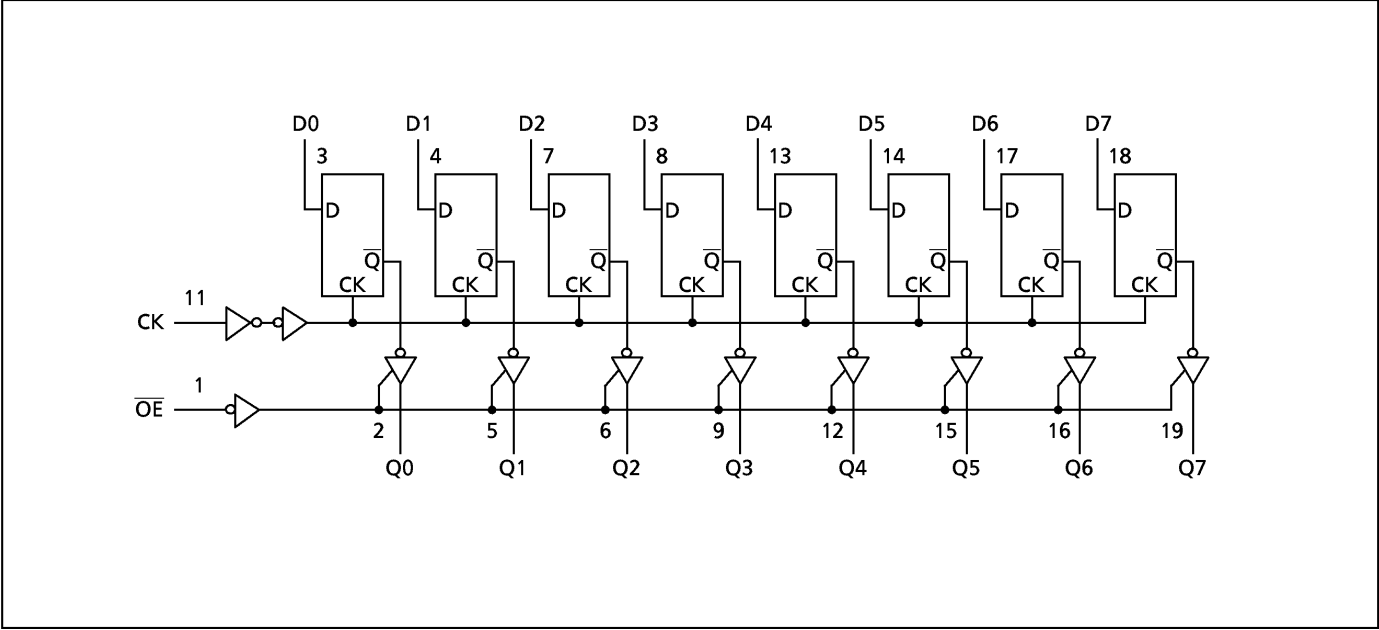
**PIN ASSIGNMENT****TRUTH TABLE**

INPUTS			OUTPUTS
$\overline{OE}$	CK	D	Q
H	X	X	Z
L		X	Q_n
L		L	L
L		H	H

X : Don't Care
Z : High Impedance
 Q_n : No Change

IEC LOGIC SYMBOL

SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7.0$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 50	mA
DC Output Current	I_{OUT}	± 50	mA
DC V_{CC} /Ground Current	I_{CC}	± 200	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	°C

*500mW in the range of $T_a = -40^\circ\text{C} \sim 65^\circ\text{C}$. From $T_a = 65^\circ\text{C}$ to 85°C a derating factor of $-10\text{mW}/^\circ\text{C}$ should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	$4.5 \sim 5.5$	V
Input Voltage	V_{IN}	$0 \sim V_{CC}$	V
Output Voltage	V_{OUT}	$0 \sim V_{CC}$	V
Operating Temperature	T_{opr}	$-40 \sim 85$	°C
Input Rise and Fall Time	dt / dV	$0 \sim 10$	ns / V

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40 \sim 85^\circ\text{C}$		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V_{IH}		4.5 5.5	2.0	—	—	2.0	—	V
Low - Level Input Voltage	V_{IL}		4.5 5.5	—	—	0.8	—	0.8	V
High - Level Output Voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -50\mu\text{A}$ $I_{OH} = -24\text{mA}$ $I_{OH} = -75\text{mA}^*$	4.5 4.5 5.5	4.4 3.94 —	4.5 — —	— — —	4.4 3.80 3.85	— — —	V
Low - Level Output Voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 50\mu\text{A}$ $I_{OL} = 24\text{mA}$ $I_{OL} = 75\text{mA}^*$	4.5 4.5 5.5	— — —	0.0 — —	0.1 0.36 —	— — —	0.1 0.44 1.65	V
3 - State Output Off - State Current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND	5.5	—	—	± 0.5	—	± 5.0	μA
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	± 0.1	—	± 1.0	
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	8.0	—	80.0	
	I_C	PER INPUT : $V_{IN} = 3.4\text{V}$ OTHER INPUT : V_{CC} or GND	5.5	—	—	1.35	—	1.5	mA

* : This spec indicates the capability of driving 50Ω transmission lines.
One output should be tested at a time for a 10ms maximum duration.

TIMING REQUIREMENTS (Input $t_r = t_f = 3\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C		Ta = -40~85°C		UNIT
			V _{CC} (V)	LIMIT	LIMIT	LIMIT	
Minimum Pulse Width (CK)	$t_{W(H)}$ $t_{W(L)}$		5.0 ± 0.5	5.0	5.0		ns
Minimum Set - up Time	t_s		5.0 ± 0.5	3.0	3.0		
Minimum Hold Time	t_h		5.0 ± 0.5	2.0	2.0		

AC ELECTRICAL CHARACTERISTICS (C_L = 50pF, R_L = 500Ω, Input $t_r = t_f = 3\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION		Ta = 25°C			Ta = − 40~85°C		UNIT
			V _{CC} (V)	MIN.	TYP.	MAX.	MIN.	MAX.	
Propagation Delay Time (CK—Q)	t _{pLH} t _{pHL}		5.0 ± 0.5	—	6.1	9.6	1.0	11.0	ns
Output Enable Time	t _{pZL} t _{pZH}		5.0 ± 0.5	—	6.2	10.1	1.0	11.5	
Output Disable Time	t _{pLZ} t _{pHZ}		5.0 ± 0.5	—	5.6	7.9	1.0	9.0	
Maximum Clock Frequency	f _{MAX}		5.0 ± 0.5	95	160	—	95	—	MHz
Input Capacitance	C _{IN}			—	5	10	—	10	pF
Output Capacitance	C _{OUT}			—	10	—	—	—	
Power Dissipation Capacitance	C _{PD} (1)			—	34	—	—	—	

Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption.

Average operating current can be obtained by the equation :

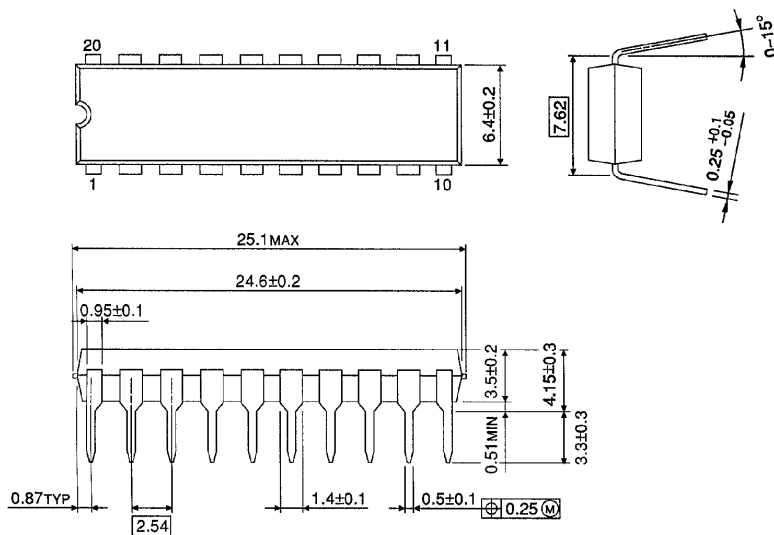
$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8 \text{ (per F/F)}$$

And the total C_{PD} when n pcs. of F/F operate can be gained by the following equation:

$$C_{PD}(\text{total}) = 22 + 12 \cdot n$$

DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)

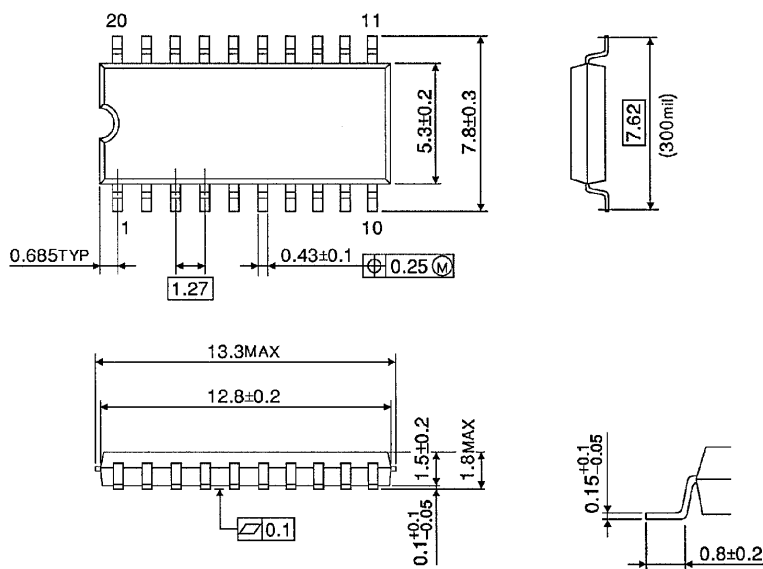
Unit in mm



Weight : 1.30g (Typ.)

SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)

Unit in mm

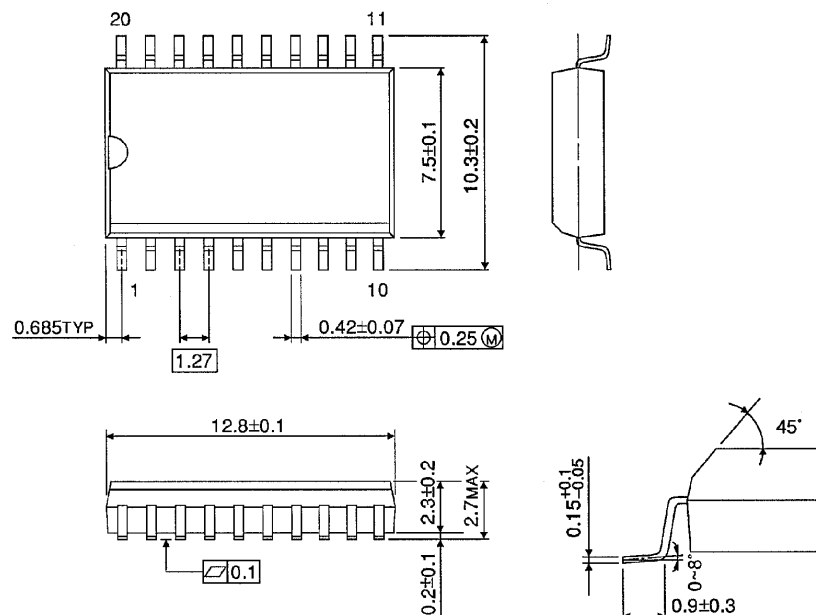


Weight : 0.22g (Typ.)

SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)

Unit in mm

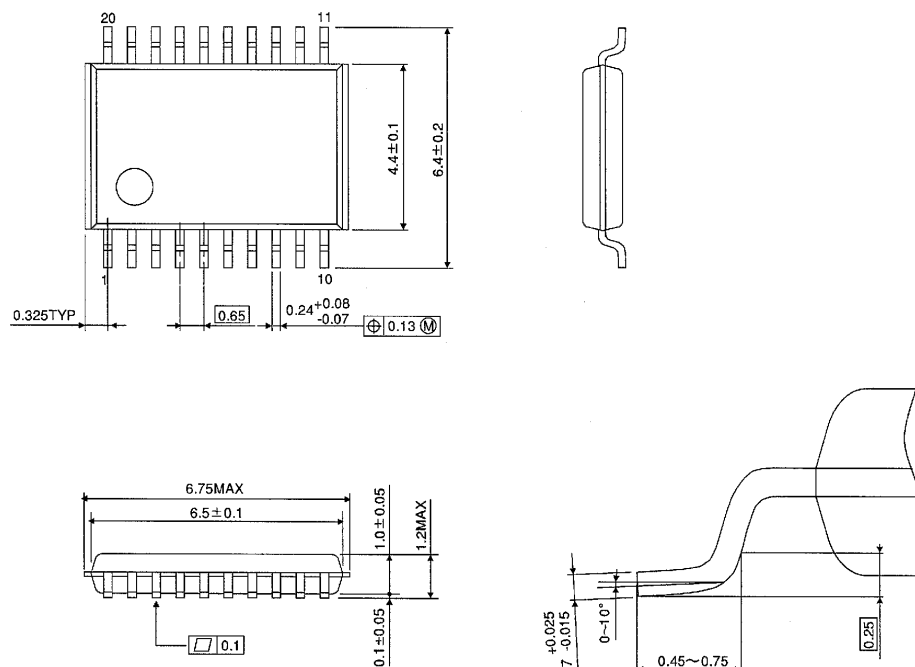
(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

TSSOP 20PIN PACKAGE DIMENSIONS (TSSOP20-P-0044-0.65)

Unit in mm



Weight : 0.08g (Typ.)

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